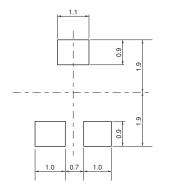
Mounting

■ Land Pattern

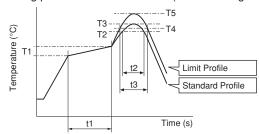


(Tolerance : ±0.1) in mm)

■ Soldering Profile

■ Reflow Soldering Profile

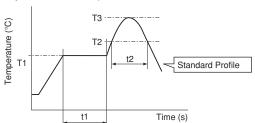
1. Soldering profile for lead free solder (96.5Sn/3.0Ag/0.5Cu)



Series	Standard Profile					Limit Profile						
	Pre-heating		Heating		Peak Temperature	Cycle of	Pre-heating		Heating		Peak Temperature	Cycle of
	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	(T3)	Reflow	Temp. (T1)	Time (t1)	Temp. (T4)	Time (t3)	(T5)	Reflow
	°C	sec.	°C	sec.	°C	Time	°C	sec.	°C	sec.	°C	Time
PVZ3	150 to 180	60 to 120	220	30 to 60	245±3	2	150 to 180	60 to 120	220	30 to 60	260	2

2. Soldering profile for Eutectic solder (63Sn/37Pb)

(Limit profile: refer to 1)



	Standard Profile								
0	Pre-h	eating	Hea	ting	Peak Temperature	Cycle of			
Series	Temp. (T1)	Time (t1)	Temp. (T2) Time (t2)		(T3)	Reflow			
	°C	sec.	°C	sec.	°C	Time			
PVZ3	150	60 to 120	183	30	230 max.	1			

Soldering Iron

g colacining non								
	Standard Condition							
Series	Temperature of Soldering Iron Tip	Soldering Time	Soldering Iron Power Output	Cycle of Soldering Iron				
	°C	sec.	W	Time				
PVZ3	350±10	3 max.	30 max.	1				